Troubleshooting for Printed Board Fabrication Processes

Amendment 2

Developed by the Printed Board Process Effects Handbook Subcommittee (7-24) of the Process Control Management Committee (7-20) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

Contact:

IPC
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New documents for Section 2 Applicable Documents

2.1 IPC

2.6.7.2 Thermal Shock, Continuity and Microsection, Printed Board
2.6.26 DC Current Induced Thermal Cycling Test
2.6.27 Thermal Stress, Convection Reflow Assembly Simulation

IPC-4552 Performance Specification for Electroless Nickel/Immersion Gold (ENIG) Plating for Printed Boards

New topics for Section 6 Mechanical Operations

6.1.2 Hole Quality

Issue: Debris in Back-Drill Hole

<table>
<thead>
<tr>
<th>CAUSE</th>
<th>ACTION</th>
</tr>
</thead>
<tbody>
<tr>
<td>Drill parameters not optimized</td>
<td>Optimize drill parameters</td>
</tr>
<tr>
<td>Potential test method (discover)</td>
<td>Potential test method (verification)</td>
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<td>Microscope inspection after back-drill</td>
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Figure 6.1.2-7